

What is claimed is:

1. A semiconductor device comprising:

a die pad;

a die pad supporter which supports said die pad;

a plurality of inner leads arranged to surround said die pad; and

a semiconductor chip which has a size larger in area than that of said die pad and which is mounted on said die pad;

wherein said die pad supporter has a stress absorbing portion which is located between said die pad and said inner leads, and wherein said semiconductor chip is disposed over the stress absorbing portion.

2. A semiconductor device according to claim 1, wherein said stress absorbing portion includes a bent portion extended in a direction different from a direction in which the die pad supporter extends.

3. A semiconductor device according to claim 1, wherein said stress absorbing portion includes a hole.

4. A semiconductor device according to claim 1, wherein said semiconductor chip is adhered to the die pad.

5. A semiconductor device comprising:

a die pad;

a die pad supporter which supports the die pad;

a plurality of inner lead arranged to surround the die pad; and

a semiconductor chip which has a size larger in area than that of said die pad and which is mounted on said die pad;

wherein said die pad supporter has a first portion, a pair of second

portions, and a pair of third portions, wherein said first portion is disposed between a pair of said inner leads and disposed substantially parallel with the pair of said inner leads, and wherein one end of each of said second portions connect one end of said first portion and said each of said second portion extend to different direction from a direction of said first portion is extended, and wherein one end of each of said third portions each connect the other end of respective said second portions and the other end of said third portions are connected to the die pad.

6. A semiconductor device comprising:

a die pad;

a die pad supporter which supports the die pad;

a plurality of leads arranged to surround the die pad; and

a semiconductor chip which has a size larger in area than that of said die pad and which is mounted on said die pad;

wherein said die pad supporter includes a frame portion which has a rectangular shape, a first portion connected between a side portion of said frame portion to the die pad, and second portions which extends from a corner portion of said frame portion, and wherein the frame portion and the first portion are disposed between the inner leads and the die pad.

7. A semiconductor device according to claim 6, wherein each of said second portions is disposed between said inner leads and disposed substantially parallel with said inner leads adjacent to the second portions.

8. A semiconductor device according to claim 7, wherein said second portions extend to four different directions.

9. A semiconductor device according to claim 6, wherein said

semiconductor chip has a first surface which is an integrated circuit is formed and a second surface which is opposite side of said first surface, and wherein said frame portion is arranged over the second surface of the semiconductor chip.

10. A semiconductor device comprising:

a die pad;

a plurality of inner leads arranged to surround the die pad;

a semiconductor chip which has a size larger in area than that of said die pad and which is mounted on said die pad;

a frame portion which substantially surrounds the die pad and disposed between said inner leads and said die pad;

first die pad supporters each of which supports the frame portion from four directions;

a second die pad supporter which connects the frame portion and die pad;

wherein said second die pad supporter is extended to different direction from directions of the first die pad supporters is extended.

11. A semiconductor device according to claim 10, wherein said semiconductor chip disposes on the frame portion.

12. A semiconductor device according to claim 11, wherein said first die pad supporter and said second die pad supporter are staggered at the frame portion.

13. A semiconductor device according to claim 10, wherein said frame portion has substantially rectangular shape, and wherein said first die pad supporter each support substantially corner portions of said frame portion,

